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### (54) MULTILAYER PRINTED WIRING BOARD AND ITS MANUFACTURING METHOD, AND RESIN COMPOSITION FOR FILLING THROUGH-HOLE

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(\*) Notice: Subject to any disclaimer, the term of this patent is extended or adjusted under 35

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This patent is subject to a terminal dis-

claimer.

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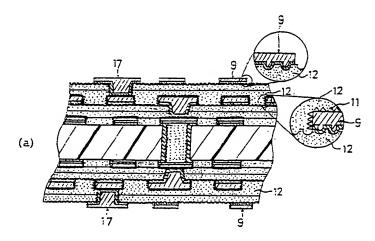
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#### (57) ABSTRACT

A multilayer printed wiring board is composed of a substrate provided with through-holes, and a wiring board formed on the substrate through the interposition of an interlaminar insulating resin layer, the through-holes having a roughened internal surface and being filled with a filler, an exposed part of the filler in the through-holes being covered with a through-hole-covering conductor layer, and a viahole formed just thereabove being connected to the through-hole-covering conductor layer. Without peeling between the through-holes and the filler, this wiring board has a satisfactory connection reliability between the through-holes and the internal layer circuit and provides a high density wiring.

## 86 Claims, 8 Drawing Sheets



0.200400